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a' emd. selectively removing said second insulating layer so as to form element isolation regions composed of the trenches filled with said second insulating layer;
removing said first insulating layer; and
selectively removing said second insulating layer using a chemical mechanical polishing (CMP) process until a surface of the conductive layer is substantially even with a surface of the second insulating layer, the conductive layer being used as a stopping layer for the CMP process.
